



Material Content Data Sheet



Sales Product Name				BSZ440N10NS3 G		Issued		19. January 2018	
MA#				MA001303190					
Package				PG-TSDSON-8-1		Weight*		36.18 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	0.830	2.29	2.29	22935	22935	
leadframe	inorganic material	phosphorus	7723-14-0	0.002	0.01		65		
	non noble metal	zinc	7440-66-6	0.009	0.03		262		
	non noble metal	iron	7439-89-6	0.189	0.52		5234		
wire	non noble metal	copper	7440-50-8	7.689	21.25	21.81	212503	218064	
	non noble metal	copper	7440-50-8	0.040	0.11	0.11	1100	1100	
	encapsulation	organic material	carbon black	1333-86-4	0.037	0.10		1029	
	plastics	epoxy resin	-	1.918	5.30		53011		
	inorganic material	silicondioxide	60676-86-0	16.667	46.08	51.48	460626	514666	
leadfinish	non noble metal	tin	7440-31-5	0.370	1.02	1.02	10228	10228	
plating	noble metal	silver	7440-22-4	0.081	0.22	0.22	2233	2233	
solder	noble metal	silver	7440-22-4	0.028	0.08		780		
	non noble metal	tin	7440-31-5	0.023	0.06		624		
	non noble metal	lead	7439-92-1	1.078	2.98	3.12	29780	31184	
heatspreader	inorganic material	phosphorus	7723-14-0	0.001	0.00		32		
	non noble metal	zinc	7440-66-6	0.005	0.01		130		
	non noble metal	iron	7439-89-6	0.094	0.26		2597		
	non noble metal	copper	7440-50-8	3.816	10.55	10.82	105463	108222	
heat sink CLIP	non noble metal	iron	7439-89-6	0.003	0.01		91		
	inorganic material	phosphorus	7723-14-0	0.001	0.00		27		
	non noble metal	copper	7440-50-8	3.302	9.12	9.13	91250	91368	
*deviation	< 10%			Sum in total:		100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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